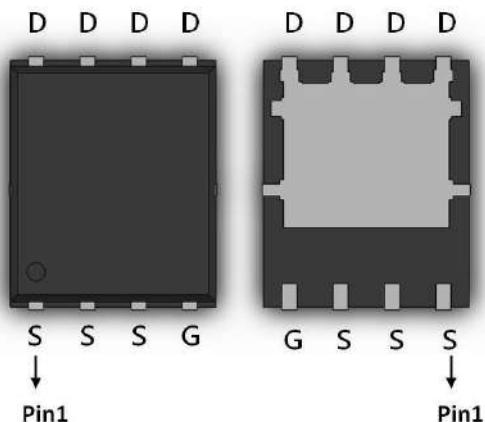


N-Channel Enhancement Mode Power MOSFET

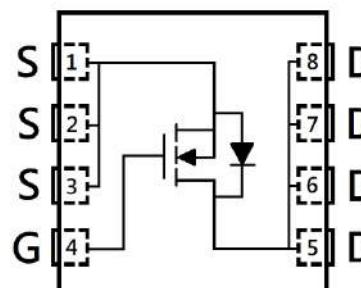
Features:

- Low On Resistance
- Low Gate Charge
- Fast Switching Characteristic

DFN5x6



BV _{DSS}	30V
I _D @V _{GS} =10V, T _c =25°C	84A
I _D @V _{GS} =10V, T _A =25°C	23A
R _{D(S)} typ. @V _{GS} =10V, I _D =20A	1.7mΩ
R _{D(S)} typ. @V _{GS} =4.5V, I _D =15A	2.3mΩ



G : Gate S : Source D : Drain

Ordering Information

Device	Package	Shipping
KPRB2D0N03R	DFN5x6 (Pb-free lead plating and halogen-free package)	3000 pcs / Tape & Reel



Absolute Maximum Ratings ($T_A=25^\circ\text{C}$)

Parameter	Symbol	Limits	Unit
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current @ $V_{GS}=10\text{V}$, $T_C=25^\circ\text{C}$ (silicon limit)	I_D	114	A
Continuous Drain Current @ $V_{GS}=10\text{V}$, $T_C=25^\circ\text{C}$ (package limit)		84	
Continuous Drain Current @ $V_{GS}=10\text{V}$, $T_C=100^\circ\text{C}$		72	
Continuous Drain Current @ $V_{GS}=10\text{V}$, $T_A=25^\circ\text{C}$		23	
Continuous Drain Current @ $V_{GS}=10\text{V}$, $T_A=70^\circ\text{C}$		18	
Pulsed Drain Current	I_{DM}	336	
Continuous Body Diode Forward Current @ $T_C=25^\circ\text{C}$	I_S	47	
Avalanche Current @ $L=0.1\text{mH}$	I_{AS}	32	
Avalanche Energy @ $L=0.5\text{mH}$	E_{AS}	100	mJ
Total Power Dissipation	$T_C=25^\circ\text{C}$	*a	W
	$T_C=100^\circ\text{C}$	*a	
	$T_A=25^\circ\text{C}$	*b	
	$T_A=70^\circ\text{C}$	*b	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55~+150	°C

Thermal Data

Parameter	Symbol	Steady State	Unit
Thermal Resistance, Junction-to-case	$R_{\theta JC}$	2.2	°C/W
Thermal Resistance, Junction-to-ambient	$R_{\theta JA}$	54	

Note:

- *a. The power dissipation P_D is based on $T_J(\text{MAX})=150^\circ\text{C}$, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.
- *b. The value of $R_{\theta JA}$ is measured with the device mounted on 1 in² FR -4 board with 2 oz. copper, in a still air environment with $T_A=25^\circ\text{C}$. The power dissipation P_D is based on $R_{\theta JA}$ and the maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.
- *c. Repetitive rating, pulse width limited by junction temperature $T_J(\text{MAX})=150^\circ\text{C}$. Ratings are based on low frequency and low duty cycles to keep initial $T_J=25^\circ\text{C}$.



Electrical Characteristics ($T_A=25^\circ C$, unless otherwise specified)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Static					
BV_{DSS}	30	-	-	V	$V_{GS}=0V, I_D=250\mu A$
$V_{GS(th)}$	1	-	2.5		$V_{DS}=V_{GS}, I_D=250\mu A$
G_{FS}	-	43	-	S	$V_{DS}=5V, I_D=20A$
I_{GSS}	-	-	± 100	nA	$V_{GS}=\pm 20V, V_{DS}=0V$
I_{DSS}	-	-	1	μA	$V_{DS}=24V, V_{GS}=0V$
$R_{DS(ON)}$	-	1.7	2.3	$m\Omega$	$V_{GS}=10V, I_D=20A$
	-	2.3	3.4		$V_{GS}=4.5V, I_D=15A$
Dynamic					
C_{iss}	-	2850	-	pF	$V_{DS}=15V, V_{GS}=0V, f=1MHz$
C_{oss}	-	2150	-		
C_{rss}	-	160	-	nC	$f=1MHz$ $V_{DS}=15V, I_D=20A, V_{GS}=4.5V$ $V_{DS}=15V, I_D=20A, V_{GS}=10V$
R_g	-	1	-		
Q_g *1, 2	-	23	-		
Q_g *1, 2	-	48	-		
Q_{gs} *1, 2	-	8.5	-		
Q_{gd} *1, 2	-	6.9	-	ns	$V_{DS}=15V, I_D=20A, V_{GS}=10V, R_{GS}=1\Omega$
$t_{d(ON)}$ *1, 2	-	18	-		
t_r *1, 2	-	14	-		
$t_{d(OFF)}$ *1, 2	-	57	-		
t_f *1, 2	-	7.5	-		
Source-Drain Diode					
V_{SD} *1	-	0.8	1.2	V	$I_S=20A, V_{GS}=0V$
tr	-	37	-	ns	$I_F=20A, dI_F/dt=100A/\mu s$
Qrr	-	28	-		

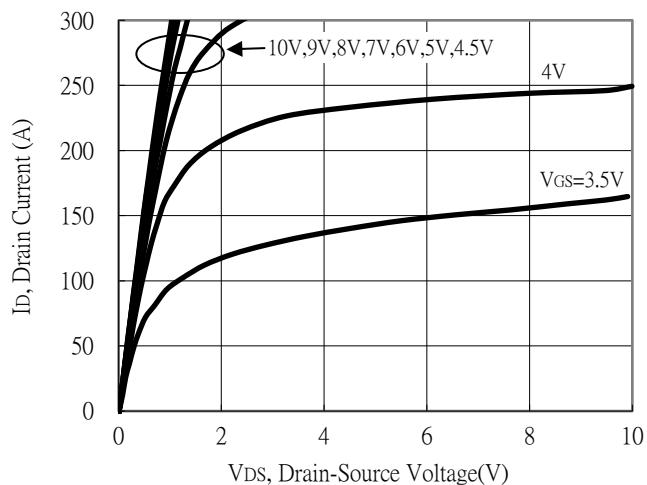
Note:

*1. Pulse Test : Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$

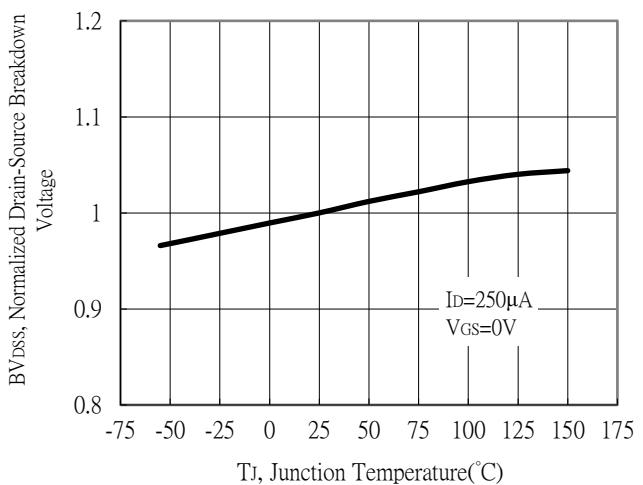
*2. Independent of operating temperature

Typical Characteristics

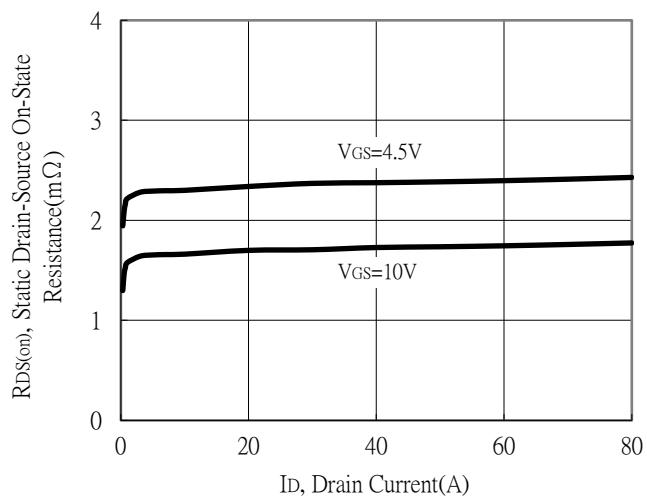
Typical Output Characteristics



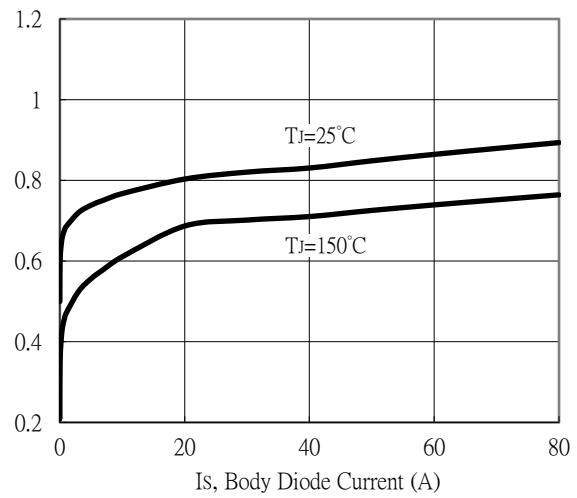
Breakdown Voltage vs Ambient Temperature



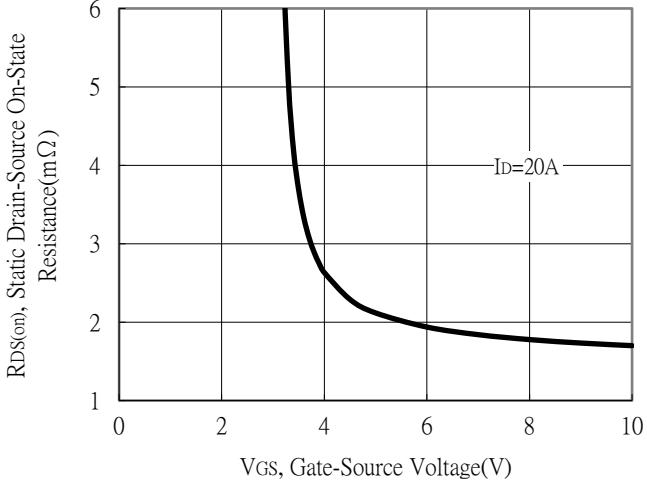
Static Drain-Source On-State resistance vs Drain Current



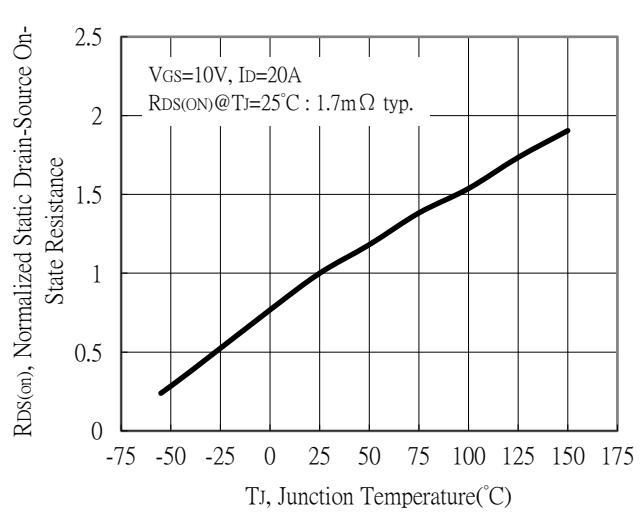
Body Diode Current vs Source-Drain Voltage



Static Drain-Source On-State Resistance vs Gate-Source Voltage

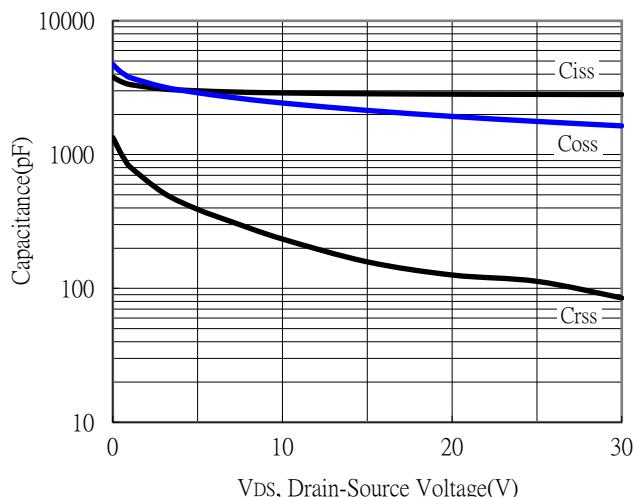


Drain-Source On-State Resistance vs Junction Temperature

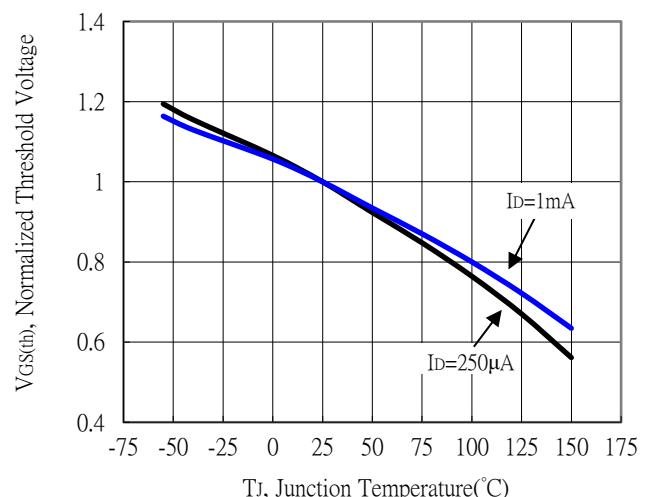


Typical Characteristics (Cont.)

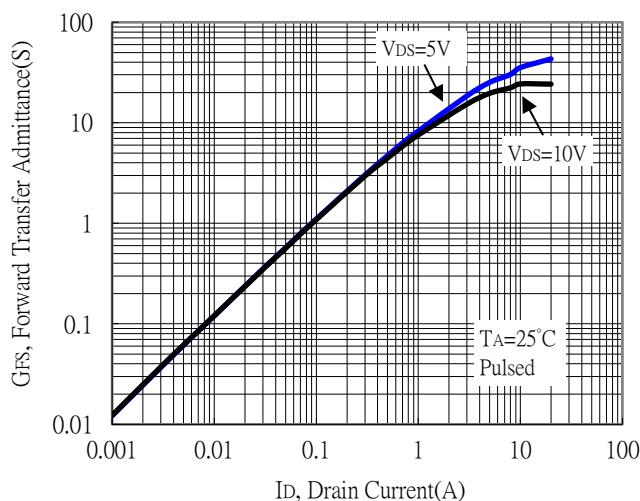
Capacitance vs Drain-to-Source Voltage



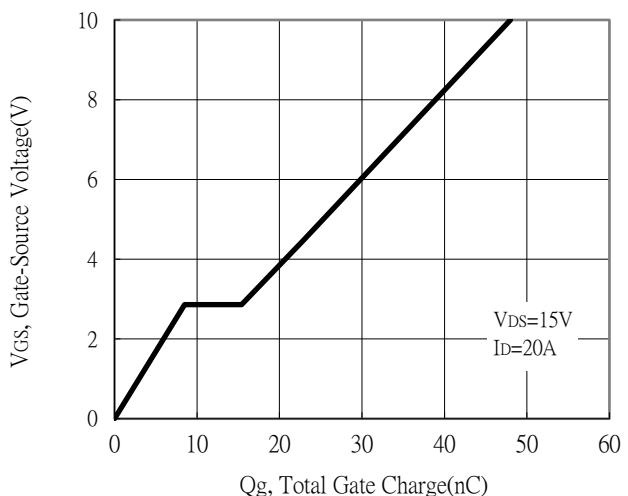
Threshold Voltage vs Junction Temperature



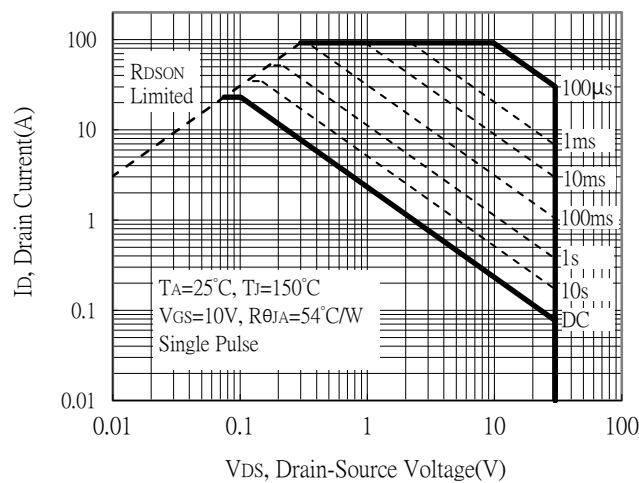
Forward Transfer Admittance vs Drain Current



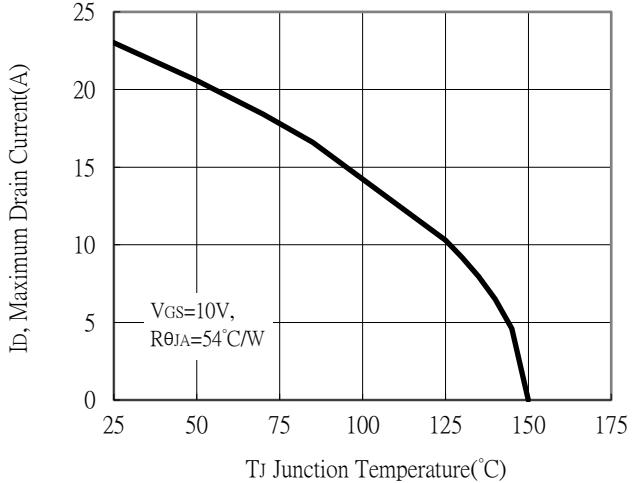
Gate Charge Characteristics



Maximum Safe Operating Area

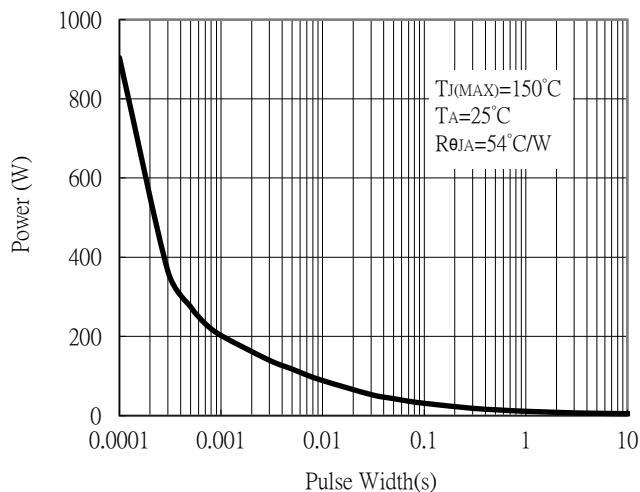


Maximum Drain Current vs Junction Temperature

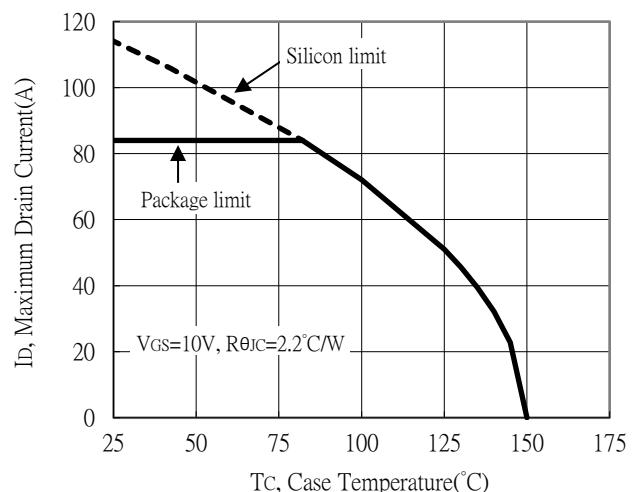


Typical Characteristics (Cont.)

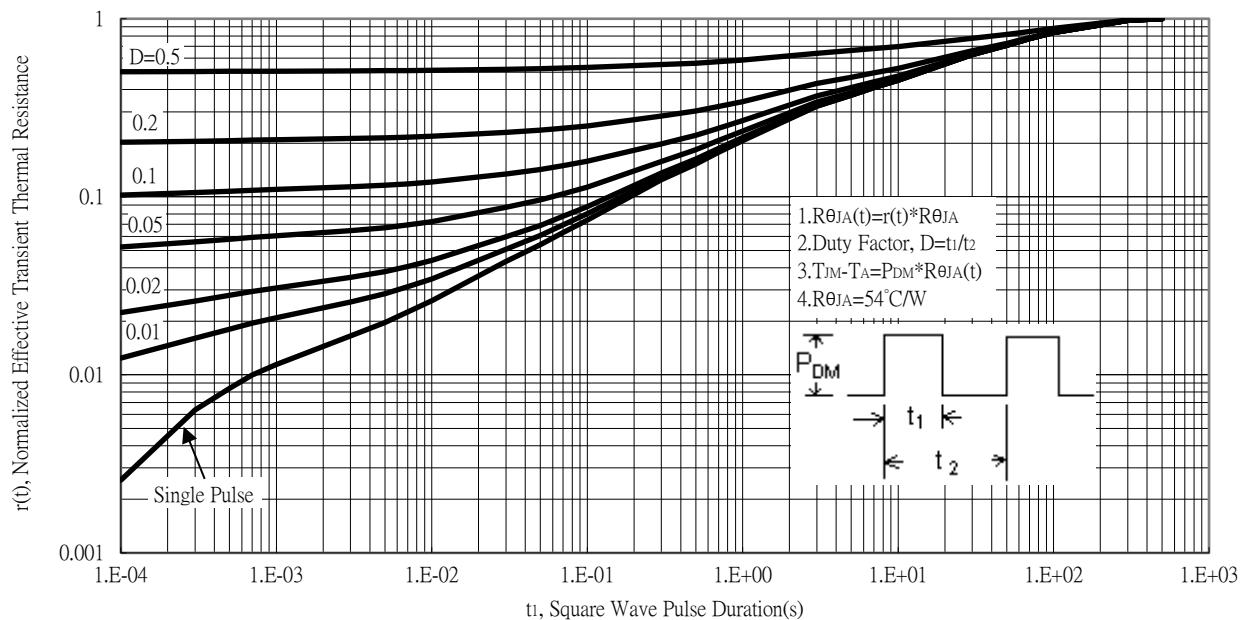
Single Pulse Power Rating, Junction to Ambient



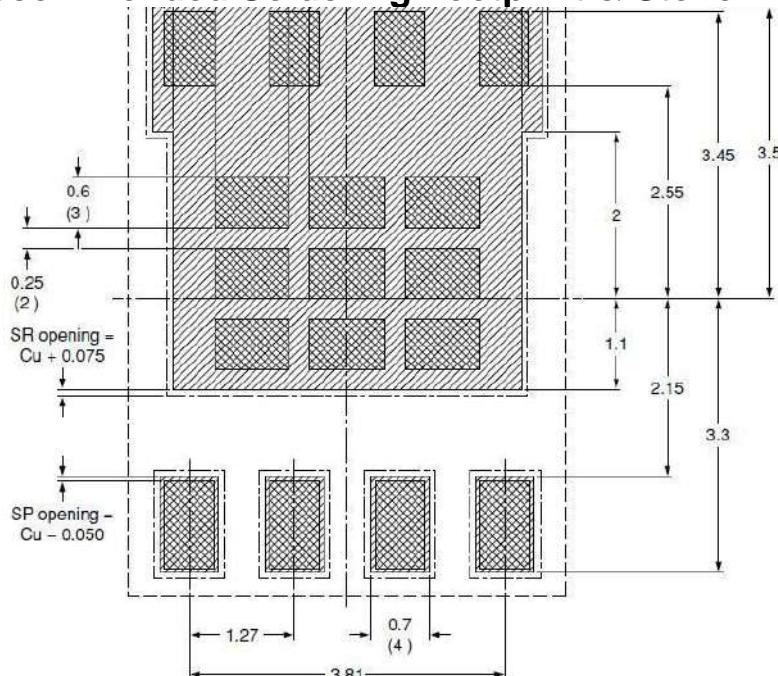
Maximum Drain Current vs Case Temperature



Transient Thermal Response Curves



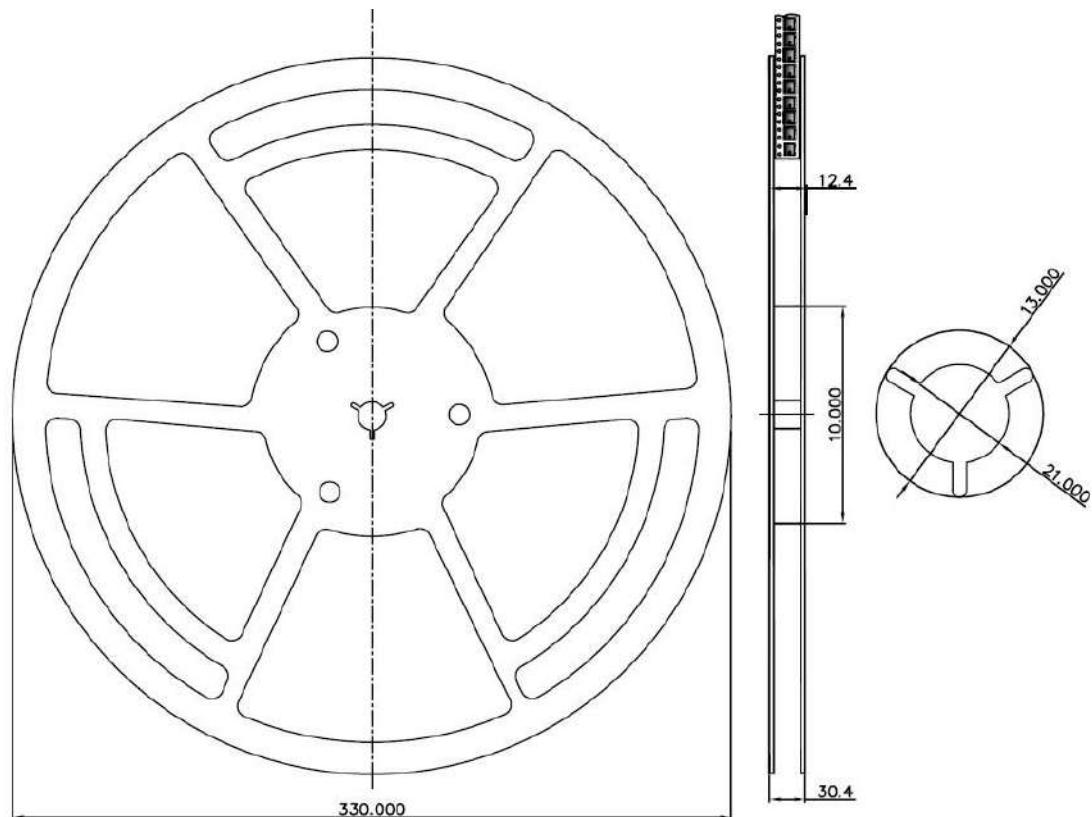
Recommended Soldering Footprint & Stencil Design



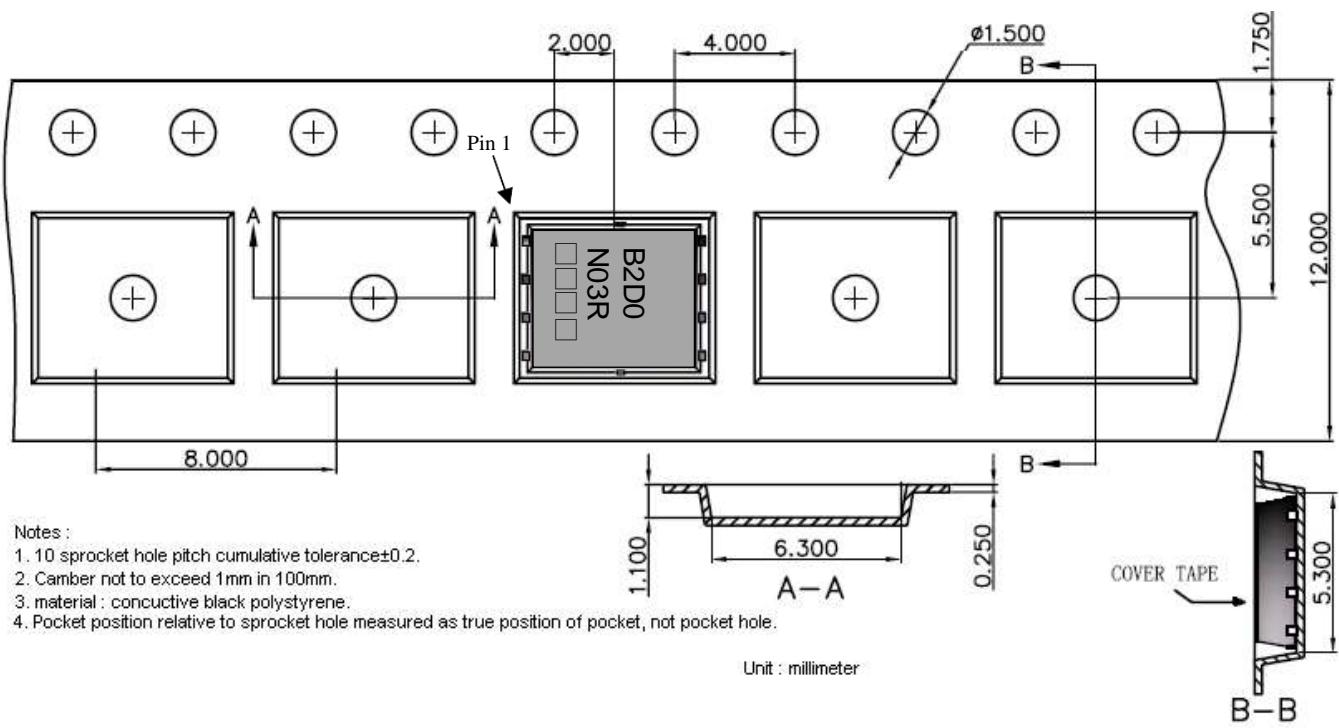
 solder lands  solder paste
 $125\text{ }\mu\text{m stencil}$
 solder resist  occupied area

unit : mm

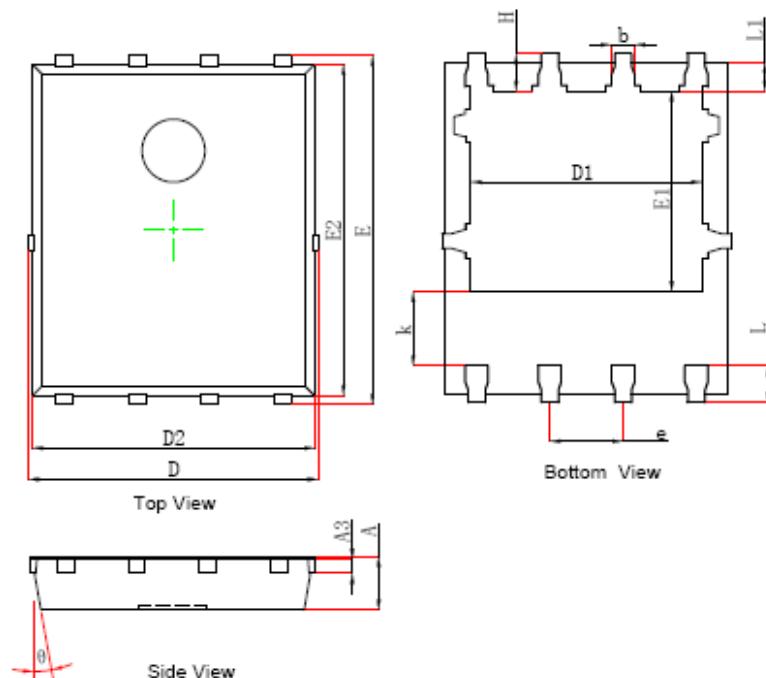
Reel Dimension



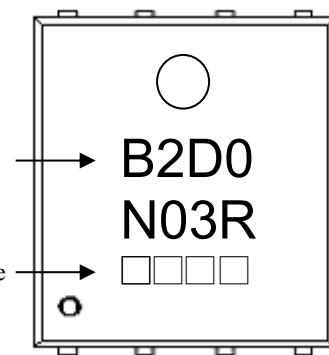
Carrier Tape Dimension



DFN5x6 Dimension (C forming)



Marking :



Date Code(counting from left to right) :

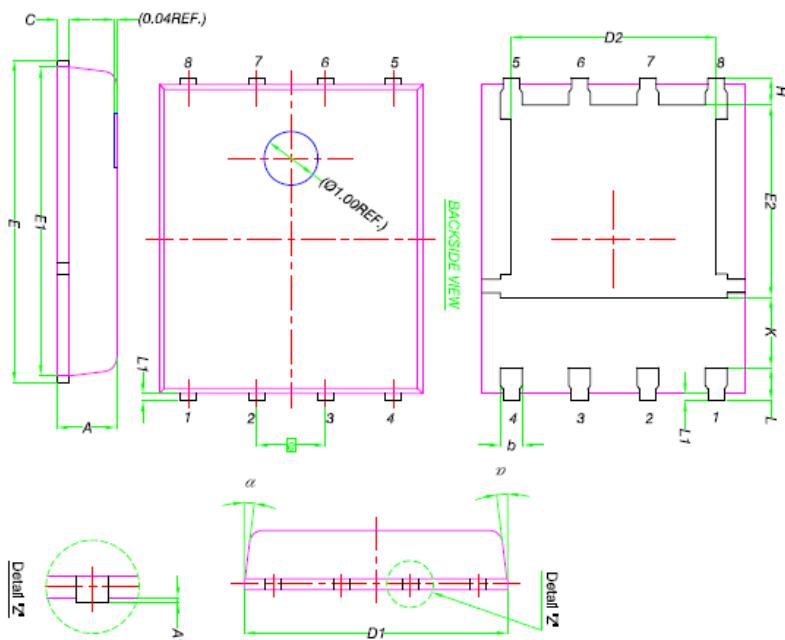
1st code: year code, the last digit of Christian year
 2nd code : month code, Jan→A, Feb→B, Mar→C,

Apr→D, May→E, Jun→F, Jul→G, Aug→H,
 Sep→J, Oct→K, Nov→L, Dec→M

3rd and 4th codes : production serial number, 01~99

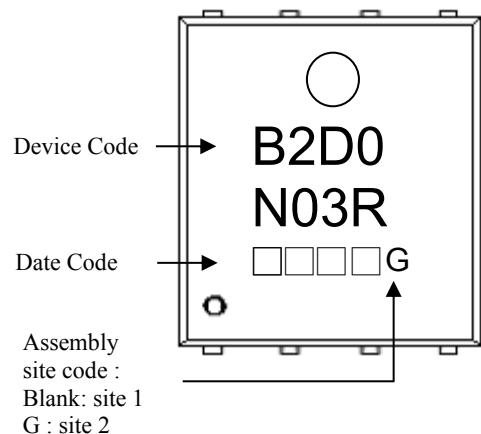
DIM	Millimeters		Inches		DIM	Millimeters		Inches	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.900	1.000	0.035	0.039	k	1.190	1.390	0.047	0.055
A3	0.254	REF	0.010	REF	b	0.350	0.450	0.014	0.018
D	4.944	5.096	0.195	0.201	e	1.270	TYP.	0.050	TYP.
E	5.974	6.126	0.235	0.241	L	0.559	0.711	0.020	0.028
D1	3.910	4.110	0.154	0.162	L1	0.424	0.576	0.017	0.023
E1	3.375	3.575	0.133	0.141	H	0.574	0.726	0.023	0.029
D2	4.824	4.976	0.190	0.196	θ	8°	12°	8°	12°
E2	5.674	5.826	0.223	0.229					

DFN5x6 Dimension (G forming)



8-Lead DFN5x6 Plastic Package

Marking:



Date Code(counting from left to right) :

1st code: year code, the last digit of Christian year
 2nd code : month code, Jan→A, Feb→B, Mar→C,

Apr→D, May→E, Jun→F, Jul→G, Aug→H,
 Sep→J, Oct→K, Nov→L, Dec→M

3rd and 4th codes : production serial number, 01~99

DIM	Millimeters		Inches		DIM	Millimeters		Inches	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.90	1.10	0.035	0.043	E2	3.38	3.78	0.133	0.149
A1	0.00	0.05	0.000	0.002	e	1.27	BSC	0.050	BSC
b	0.33	0.51	0.013	0.020	H	0.41	0.61	0.016	0.024
C	0.20	0.30	0.008	0.012	K	1.10	-	0.043	-
D1	4.80	5.00	0.189	0.197	L	0.51	0.71	0.020	0.028
D2	3.61	3.96	0.142	0.156	L1	0.06	0.20	0.002	0.008
E	5.90	6.10	0.232	0.240	α	0°	12°	0°	12°
E1	5.70	5.80	0.224	0.228					